ISMP-IRSP 2024 Poster Presentaion | Nov 7, 2024 (Thu) 09:00~18:00 | Grand Ballroom

ID	Reg.	Title	Presenter	Affiliation	Country
1. Novel Packaging Technologies					
P1-01	ABST-000198	Strain-Visualization with Ultrasensitive Nanoscale Crack-Based Sensor Assembled with Hierarchical Thermochromic Membrane	OK JEHYUNG	SUNGKYUNKWAN UNIVERSITY	KOR
P1-02	ABST-000192	Strain-resilient modular electronic circuits and systems using liquid metal	GYAN RAJ KOIRALA	SUNGKYUNKWAN UNIVERSITY	KOR
P1-03	ABST-000178	Pressureless Silver Bimodal paste Sintering Technology for superior-strength Bonding of Power Semiconductor	GU MOSES	SEOUL NATIONAL UNIVERSITY OF SCIENCE AND TECHNOLOGY	KOR
P1-04	ABST-000173	Strain-Insensitive Touch Screen Panel using Porous Structure	KIM KYEONGTAE	HANYANG UNIVERSITY	KOR
P1-05	ABST-000172	Deep Learning-Based Phase Map Implementation and Deformation Measurement in Packaging from Single Images	HONG HYEONUI	KOREA UNIVERSITY OF TECHNOLOGY AND EDUCATION	KOR
P1-06	ABST-000142	Development of a Biocompatible, Hydrophilic Soft Cranial Window for Enhanced In Vivo Brain Imaging	KIM JIWON	SUNGKYUNKWAN UNIVIRSITY	KOR
P1-07	ABST-000133	Wearable EEG electronics for a Brain–AI Closed-Loop System to enhance autonomous machine decision-making	JUNE KEONUK	SUNGKYUNKWAN UNIVERSITY	KOR
P1-08	ABST-000114	Enhancing Solderability of Printed Circuit Boards through Plasma Treatment: A Sustainable Approach to Surface Treatment Optimization	LEE CHEOL	SUNGKYUNKWAN UNIVERSITY	KOR
P1-09	ABST-000109	Ball Grid Array(BGA) Design and Signal Integrity(SI) Analysis for High-Speed Transmission Interface	CHAE SUIN	KOREA ELECTRONICS TECHNOLOGY INSTITUTE (KETI)	KOR
P1-10	ABST-000092	Fabrication of Ion Gels with Enhanced Side-chain Crystallization	CHOI SOHYUN	INHA UNIVERSITY	KOR
P1-11	ABST-000088	Driving force for enhancing the cold silver sinter joining at 175 °C using time domain-dependent Ag-Au epitaxy and interfacial stress	KIM DONGJIN	KOREA INSTITUTE OF INDUSTRIAL TECHNOLOGY (KITECH)	KOR
P1-12	ABST-000087	Flux-Less Solder Ball Attachment Technology (FLAT) for Advanced BGA Assembly	KIM DONGJIN	KOREA INSTITUTE OF INDUSTRIAL TECHNOLOGY (KITECH)	KOR
P1-13	ABST-000085	Oxidation-free cold Cu sinter joining in the air	KIM DONGJIN	KOREA INSTITUTE OF INDUSTRIAL TECHNOLOGY (KITECH)	KOR
P1-14	ABST-000080	Machine Learning-Based Indentation Tensile Properties Using Finite Element Analysis Considering the 3D Profile of the Spherical Tip	KIM DONG-YEOB	ANDONG NATIONAL UNIVERSITY	KOR
P1-15	ABST-000074	Effect of Ar/N2 Two-step Plasma Treatment on the Interfacial Adhesion Energy of SiO2-SiO2 Interface for Low-Temperature Hybrid Bonding	JUNG YEONWOO	ANDONG NATIONAL UNIVERSITY	KOR
P1-16	ABST-000054	Dry Desmear Process for Advanced Packaging Substrate	KIM GYULEE	HANYANG UNIVERSITY	KOR
P1-17	ABST-000053	Impact of TSV Configuration on Thermal Performance of High Bandwidth Memory	CHOI JAEYOUNG	HANYANG UNIVERSITY	KOR
P1-18	ABST-000048	High-Frequency Transmission Line Performance: Minimizing Degradation through Parylene Passivation	CHO YOUNGBEEN	KOREA ELECTRONICS TECHNOLOGY INSTITUTE (KETI)	KOR
P1-19	ABST-000046	Laser Assisted Bonding (LAB) technology Using Laser Non-Conductive Paste (NCP) for Micro solder bumps	JANG KI-SEOK	ELECTRONICS AND TELECOMMUNICATIONS RESEARCH INSTITUTE (ETRI)	KOR
P1-20	ABST-000027	Influence of Oxide Layer Thickness on Head-in-Pillow Defects in SAC 305 Solder Balls and Mitigation Techniques	SHIN TAEK-SOO	SUNGKYUNKWAN UNIVERSITY	KOR
P1-21	ABST-000024	Low-temperature curing, high-strength resin-coated copper for glass packaging substrates	KIM SEONWOO	SUNGKYUNKWAN UNIVERSITY	KOR
P1-22	ABST-000022	A Study on high ASIL on Chip Packaging for Automotive System on Chip	YEON KYUBONG	KOREA AUTOMOTIVE TECHNOLOGY INSTITUTE (KATECH)	KOR
P1-23	ABST-000021	A Study on the interference systems of automotive 4D imaging radar with on packaging	YEON KYUBONG	KOREA AUTOMOTIVE TECHNOLOGY INSTITUTE (KATECH)	KOR
P1-25	ABST-000076	Improve deep tooth problem in wet desmear by applying dry desmear method	JEONG SOONOH	LG INNOTEK	KOR
P1-26	ABST-000200	UV-Induced Debonding Characteristics of Acrylic Pressure Sensitive Adhesives and Surface Characterization after Debonding	KIM KYEONGMIN	CHUNGNAM NATIONAL UNIVERSITY	KOR
P1-27	ABST-000191	Research on bonding pattern design of Cu-SiO2 Hybrid Bonding for Heterogeneous Integration	KIM KI-CHEOL	KANGNAM UNIVERSITY	KOR
P1-28	ABST-000187	Evaluation of electrical properties of Cu-Cu bonding in Hybrid bonding	LEE SIYE	SEOUL NATIONAL UNIVERSITY OF SCIENCE AND TECHNOLOGY	KOR
P1-29	ABST-000176	3D heterogeneous integrated flexible interposer based on polyimide for high-performance computing	LEE MYUNGWON	HANYANG UNIVERSITY	KOR
P1-30	ABST-000117	Optimization of Additives to Fabricate Fine-Grained Cu via Electroplating for Cu-Cu Direct Bonding	SON JUN-HEE	SUNGKYUNKWAN UNIVERSITY	KOR
2. Materials for Interconnects and Packaging					
P2-01	ABST-000189	Ag Sintered Joints Thickness Effects on Mechanical Properties and Thermal Reliability for Power Semiconductor	YU MIN-JI	KOREA INSTITUTE OF INDUSTRIAL TECHNOLOGY (KITECH)	KOR
P2-02	ABST-000184	Evaluation on Interfacial Properties of Joint between Sn-Ag-Cu and Sn-Bi-Ag Pb-free Solders by Induction Heating	KIM JAHYEON	KOREA INSTITUTE OF INDUSTRIAL TECHNOLOGY (KITECH)	KOR
P2-03	ABST-000163	Microstructural Evolution and Mechanical Behavior of Sn-Ag-Co Composite Solder in Electric Vehicle Power Modules via Two-Step TLP Bonding	KIM BYUNGWOO	CHOSUN UNIVERSITY	KOR
P2-04	ABST-000160	Effect of Epoxy Composites on Thermal and Mechanical Properties of Hybrid Ag Paste for Pressure-Assisted Sintering	JEONG JE-YONG	KOREA INSTITUTE OF INDUSTRIAL TECHNOLOGY (KITECH)	KOR
P2-05	ABST-000156	Flexible and Electrically An-isotropic Conductive Liquid Metal Adhesive for 3D Integration Process	LEE SANGGIL	SUNGKYUNKWAN UNIVERSITY(SKKU)	KOR
P2-06	ABST-000154	Effect of pre-cleaning of Ag surface finish on the Ag sintering behavior	YU MINJU	KOREA INSTITUTE OF INDUSTRIAL TECHNOLOGY (KITECH)	KOR
P2-07	ABST-000152	Effects of TiC nanoparticle addition on properties of Sn58Bi/Sn3.0Ag0.5Cu hybrid solder joints for low-temperature electronic packaging	LIM KWAN-SOO	CHUNGBUK NATIONAL UNIVERSITY	KOR
P2-08	ABST-000150	Transient Liquid Phase Bonding Using Sn-Ni-Sn Metal Composite Preform and the Long-term Reliability of the Joint	LEE DONG-BOK	CHUNGBUK NATIONAL UNIVERSITY	KOR
P2-09	ABST-000148	Investigation of Au and Ag Plating Layers for Low Temperature Cu-Cu Bonding	BAEK SONG-YEON	CHUNGBUK NATIONAL UNIVERSITY	KOR
P2-10	ABST-000147	Interfacial reactions of Sn-Ag/Cu pillar bump joints with Ni insertion layer fabricated by intense pulsed light soldering	NOH EUN-CHAE	CHUNGBUK NATIONAL UNIVERSITY	KOR
P2-11	ABST-000146	Effect of Cu microstructure on interfacial compounds formation and growth in Sn-3.0Ag-0.5Cu solder joints	HAN DA-GYEONG	CHUNGBUK NATIONAL UNIVERSITY	KOR

P2-12	ABST-000139	Enhanced Thermal Conductivity in BN Composite Films for Highly Integrated Electronics and Flexible Devices	MUN YUJIN	SUNGKYUNKWAN UNIVERSITY	KOR
P2-13	ABST-000137	Study on the Behavior and Microstructure Analysis of Through-Hole Via Fill Based on Time and Additive Type	LEE EUN-BI	KUMOH NATIONAL INSTITUTE OF TECHNOLOGY	KOR
P2-14	ABST-000107	Evaluation on Effects of Printing Aspect Ratio of Sn-57Bi-1Ag Solder Paste on Interface Properties with Sn-3.0Ag-0.5Cu Solder	IM TAEYOON	KOREA INSTITUTE OF INDUSTRIAL TECHNOLOGY (KITECH)	KOR
P2-15	ABST-000101	Material with superior thermal conductivity for microelectronics package	KIM DONGKYU	KOREA ADVANCED INSTITUTE OF SCIENCE AND TECHNOLOGY (KAIST)	KOR
P2-16	ABST-000089	Solid-state bonding with rolled SAC305 sheets for direct cooling	JO EUNJIN	KOREA INSTITUTE OF INDUSTRIAL TECHNOLOGY (KITECH)	KOR
P2-17	ABST-000086	Steady-state thermomechanical degradation physics of cold silver nanoporous sheet bonding onto direct Ag finish to withstand T_j = 250 °C in SiC power inverters	KIM DONGJIN	KOREA INSTITUTE OF INDUSTRIAL TECHNOLOGY (KITECH)	KOR
P2-18	ABST-000066	Adhesion improvement between Solder resist and Cu bonding pad	LEE YONGJUN	LG INNOTEK	KOR
P2-19	ABST-000065	Effect of Palladium on the Morphological Changes of Intermetallic Compounds in ENEPIG Surface Finish	JIN HYERIN	SUNGKYUNKWAN UNIVERSITY	KOR
P2-20	ABST-000064	Compositional modification of $(Ni_xCo_yMn_{3-x-y})O_4$ by adding V_2O_5 and Evaluation of Applicability to Temperature Sensor	LEE JIN-YOUNG	KYONGGI UNIVERSITY	KOR
P2-21	ABST-000062	Development of Epoxy-Based Solder Paste and Simultaneous Transfer and Bonding Process for Flexible Full-Color Mini/Micro-LED Displays	LEE CHANMI	ELECTRONICS AND TELECOMMUNICATIONS RESEARCH INSTITUTE (ETRI)	KOR
P2-22	ABST-000056	A Comparative Study of Mass Reflow(MR) and Laser Assisted Bonding(LAB) of Sn-Ag-Cu Solder on Ni-less Surface Finishes	HAN SEONGHUI	KOREA INSTITUTE OF INDUSTRIAL TECHNOLOGY (KITECH)	KOR
P2-23	ABST-000055	Morphology changes of multidimensional organic-inorganic perovskite thin films influenced by relative humidity	LEE SUMIN	CHUNGNAM NATIONAL UNIVERSITY	KOR
P2-24	ABST-000047	Mechanical and Electrochemical Properties of Ni-Rich NCM Cathode Material for Lithium-Ion Batteries with Photo-lithography Using Nanoindentation Testing	PARK JIHYEON	ANDONG NATIONAL UNIVERSITY	KOR
P2-25	ABST-000038	A Study on the Improving Contact Angle & Taper Angle of Black Matrix for OLED Display	JEONG YEONGGWON	KOREA ELECTRONICS TECHNOLOGY INSTITUTE (KETI)	KOR
P2-26	ABST-000037	Effects of diffusion barrier electrodes on back end of line (BEOL) Cu integration with polyimides	CHOI KYEONG-KEUN	POHANG UNIVERSITY OF SCIENCE AND TECHNOLOGY (POSTECH)	KOR
P2-27	ABST-000035	Analysis of Transmission Characteristics Based on Surface Finish Materials	SEO DEOKJIN	KOREA ELECTRONICS TECHNOLOGY INSTITUTE (KETI)	KOR
P2-28	ABST-000019	Ceramic/epoxy composites for enhancing the heat dissipation in IC packages: Experimental and mathematical modeling analyses	AL SALIM ABDALLAH	SUNGKYUNKWAN UNIVERSITY	KOR
P2-29	ABST-000008	Development and Characterization of Low-k Polyimide-Based Material with Low-Temperature Curing for High-Frequency Electronic Components	NAM HYUN JIN	KOREA ELECTRONICS TECHNOLOGY INSTITUTE (KETI)	KOR
P2-30	ABST-000005	Electrochemical Growth of Cu Single Crystals in Micrometer-scale patterned substrate	JEONG GIHO	POHANG UNIVERSITY OF SCIENCE AND TECHNOLOGY (POSTECH)	KOR
P2-31	ABST-000002	Growth Kinetics and Morphology Evolution due to Reactive Diffusion at Cu/(Sn-Bi-X) Interface	OH MINHO	TOKYO INSTITUTE OF TECHNOLOGY	JPN
3. Advanced Packaging Process					
P3-01	ABST-000193	Fabrication of a Two-Layer RDL with Polymeric Dielectrics for RDL Interposer Applications	KANG MINJI	SEOUL NATIONAL UNIVERSITY OF SCIENCE AND TECHNOLOGY	KOR
P3-02	ABST-000183	Optimization of Flip-Chip Substrate Patterning with 30 um Bump Pitch for Ni-Less Surface finishes Evaluation	LEE TAE-YOUNG	TECH UNIVERSITY OF KOREA	KOR
P3-03	ABST-000180	Nanoscale Dewetting-Driven Direct Interconnection of Microelectronics for Precise Assembly in Transfer Printing	KIM KYUNGMIN	SUNGKYUNKWAN UNIVERSITY	KOR
P3-04	ABST-000179	Implantable micro-LED Device for Controlled Photodynamic Therapy	OH SUYOUN OH	SUNGKYUNKWAN UNIVERSITY	KOR
P3-05	ABST-000177	A Liquid Metal Mediated Metallic Coating for Antimicrobial and Antiviral Fabrics	KWAK CHAERIN	SUNGKYUNKWAN UNIVERSITY	KOR
P3-06	ABST-000174	Optimizing Intense Pulsed Light Soldering Conditions for Micro-Bump Applications: A Comparative Study with Reflow Process	GO YEONJU	SAMSUNG ELECTRONICS	KOR
P3-07	ABST-000171	Gelatin Hydrogel-Based Organic Electrochemical Transistors and Their Integrated Logic Circuits	CHOI SUNGBIN	SUNGKYUNKWAN UNIVERSITY	KOR
P3-08	ABST-000170	Chemo-photodynamic Glioma Treatment Using Implantable Micro-LED and Drug Delivery System	LEE JUN SEO	SUNGKYUNKWAN UNIVERSITY	KOR
P3-09	ABST-000167	Correlation Analysis between Etching Factor and Circuit Impedance	IM YOUNGMIN	KOREA ELECTRONICS TECHNOLOGY INSTITUTE (KETI)	KOR
P3-10	ABST-000166	Effect of heater pattern design on semiconductor electrostatic chuck for optimizing surface temperature uniformity	KIM SANG-HOON	MYONGJI UNIVERSITY	KOR
P3-11	ABST-000164	Numerical study of curing process using Maxwell model	KIM KYEONG-BIN	SUNGKYUNKWAN UNIVERSITY	KOR
P3-12	ABST-000162	Implantable MicroLED-mediated Chemo-photodynamic Combination Therapy for Glioma Treatment	LEE HIN KIU	SUNGKYUNKWAN UNIVERSITY	KOR
P3-13	ABST-000161	Hybrid PDMS stamp for Micro-LED Transfer	AHN SEOL	HANYANG UNIVERSITY	KOR
P3-14	ABST-000159	A Liquid Metal Mediated Metallic Coating on Fabric	MING YONG	SUNGKYUNKWAN UNIVERSITY	KOR
P3-15	ABST-000157	Preventing the formation of cracks in 2.5D glass interposers during the annealing process	LE XUAN-BACH	SEOUL NATIONAL UNIVERSITY OF SCIENCE AND TECHNOLOGY	KOR
P3-16	ABST-000145	Intense pulsed light soldering properties of Sn-Ag-Cu solder joints and comparison to traditional reflow soldering	LEE HYO-WON	CHUNGBUK NATIONAL UNIVERSITY	KOR
P3-17	ABST-000144	Fibrillary PEDOT:PSS Nanofiber Mat Electrode for Enhanced Conductivity and Durable Skin-Adaptable Electronics	SHIN YOUNGKWANG	SUNGKYUNKWAN UNIVIRSITY	KOR
P3-18	ABST-000113	Al FPCB/Cu FPCB lap joint using Ag sinter joining	LEE YEHWAN	KOREA INSTITUTE OF INDUSTRIAL TECHNOLOGY (KITECH)	KOR
P3-19	ABST-000110	Reducing Sidewall Roughness of Through Silicon Via Created Using Femtosecond Lasers with MHz-Burst and Single Pulse Modes	KIM TAESIK	KOREA INSTITUTE OF INDUSTRIAL TECHNOLOGY (KITECH)	KOR
P3-20	ABST-000099	Development and Performance Evaluation of Low-Cost Photopolymer Resin Waveguides Utilizing 3D Printing Technology	SEO MIRAE	KOREA ELECTRONICS TECHNOLOGY INSTITUTE (KETI)	KOR
P3-21	ABST-000093	Low-temperature Intense Pulsed Light (IPL) Soldering of Cu Pillar Bumps with Sn-58Bi Leadfree Solder	GO HYERI	CHOSUN UNIVERSITY	KOR
P3-22	ABST-000091	Measurement of wafer-to-wafer direct bonding strength for chip-scale specimen by Chevron-notch test	LEE SANGMIN	OSAKA UNIVERSITY	JPN

P3-23	ABST-000079	Dry Etching Process for Via Formation in Build-up Film Substrate	KIM SUNBUM	HANYANG UNIVERSITY	KOR
P3-24	ABST-000052	Demonstration of Integrated Passive Devices in Glass Substrates Using TGV Process	YI SANGHO	KOREA ELECTRONIC TECHNOLOGY INSTITUTE	KOR
P3-25	ABST-000050	Influence of Bismuth Diffusion on the Properties and Reliability of Low-Temperature Solder	YOON JAE JUN	SUNGKYUNKWAN UNIVERSITY	KOR
P3-26	ABST-000045	Effect of Viscoelastic-anisotropic Properties of Prepreg on Diagonal Warpage of Multilayer PCB Substrates	GU CHANG-YEON	KOREA ADVANCED INSTITUTE OF SCIENCE AND TECHNOLOGY (KAIST)	KOR
P3-27	ABST-000043	Fabrication of Octagonal-shaped Bi-cell Si Photodiode for Ultra-compact Polarization Angle Detector	LEE EO JIN	HANBAT NATIONAL UNIVERSITY	KOR
P3-28	ABST-000036	The Study of Copper-to-Copper direct bonding process using Current-induced enhancement method	KWAK BYUNGKWAN	HANYANG UNIVERSITY	KOR
P3-29	ABST-000034	Impact of Laser-Assisted Bonding Parameters on Joint Properties of 40 µm Pitch Cu/SnAg Pillar Bumps on Ni-less Surface Finish	HAN SANGEUN	KOREA INSTITUTE OF INDUSTRIAL TECHNOLOGY (KITECH)	KOR
P3-30	ABST-000030	Development of a Lithium-Reduced Charge Generation Layer with Metal Interlayer for Tandem OLED Applications	SUH YO-HAN	KOREA ELECTRONICS TECHNOLOGY INSTITUTE (KETI)	KOR
P3-31	ABST-000014	Low-temperature Hybrid Bonding with Photosensitive Polymer Insulation for Advanced Packaging	SIM YOUNGJU	UNIST	KOR
4. Reliability of Electronic Devices and Systems					
P4-01	ABST-000199	A study on Power Integrity Test of Multi-layer Printed Circuit Board(PCB) for Burn-in Testing of High Speed Memory	KIM SUNG YONG	TECH UNIVERSITY OF KOREA	KOR
P4-02	ABST-000197	Measurement method comparison of coefficients of thermal expansion in semiconductor materials by using thermomechanical analysis and digital image correlation	KIM SEUNGBIN	MYONGJI UNIVERSITY	KOR
P4-03	ABST-000158	Investigating crack generation in hybrid bonding structures during the post-bonding annealing process	LE XUAN-BACH	SEOUL NATIONAL UNIVERSITY OF SCIENCE AND TECHNOLOGY	KOR
P4-04	ABST-000153	Metallurgical interfacial reaction and mechanical long-term reliability evaluation of Sn-Ag/Ni UBM flip-chip solder bump joints with high-temperature aging	JANG EUN-SU	CHUNGBUK NATIONAL UNIVERSITY	KOR
P4-05	ABST-000141	Fully Modifiable Fabric-Based Liquid Metal Soft Circuit Board	JEONG CHANHO	SUNGKYUNKWAN UNIVERSITY	KOR
P4-06	ABST-000140	Data-driven multiscale analysis technique for epoxy nanocomposites using transfer learning	LEE WONJOO	INHA UNIVERSITY	KOR
P4-07	ABST-000138	Cuticular pad–inspired selective frequency damper for nearly dynamic noise–free bioelectronics	YANG YE JI	SUNGKYUNKWAN UNIVERSITY	KOR
P4-08	ABST-000136	Effect of Interfacial Adhesion on fatigue Deformation of Cu interconnect	HEO JEONG A	KUMOH NATIONAL INSTITUTE OF TECHNOLOGY	KOR
P4-09	ABST-000131	Chronic and acute stress monitoring by electrophysiological signals from adrenal gland	GUO LILI	SUNGKYUNKWAN UNIVERSITY	KOR
P4-10	ABST-000125	High Temperature Reliability of Sintered Cu@Ag Joints for WBG Power Electronics Packaging with AI-assisted Package Reliability Prediction Model	JEONG GEON-JOO	KOREA INSTITUTE OF INDUSTRIAL TECHNOLOGY (KITECH)	KOR
P4-11	ABST-000124	Analysis of transmission loss of stripline according to impedance	KIM KYUNGSUN	KOREA ELECTRONICS TECHNOLOGY INSTITUTE (KETI)	KOR
P4-12	ABST-000123	Study of WS2 diffusion barrier for the Suppression of Cu for interconnect reliability in advanced packing	CHAVAN VIJAY D.	SEJONG UNIVERSITY	KOR
P4-13	ABST-000122	Highly Robust Bulge Sandwich and Sandwich Metallization Systems of different Metallization Systems investigated by Simulation	WEIDE-ZAAGE KIRSTEN	LEIBNIZ UNIVERSITÄT HANNOVER	DEU
P4-14	ABST-000120	Microscale failure prediction for thermal fatigue damage in fine pitch solder bump of flip chip package	CHOI SEONGKYU	KOREA INSTITUTE OF INDUSTRIAL TECHNOLOGY (KITECH)	KOR
P4-15	ABST-000106	Simulation of SiC MOSFET for Power Module with Several structures	KIM SHIN WOO	INHA UNIVERSITY	KOR
P4-16	ABST-000104	Reliability Evaluation of Indium Solder Joints using Laser-Assisted Bonding (LAB) Process and Laser Non-Conductive Paste (NCP)	JUNG JI EUN	ELECTRONICS AND TELECOMMUNICATIONS RESEARCH INSTITUTE (ETRI)	KOR
P4-17	ABST-000097	Enhanced warpage and heat dissipation for fan-out package with embedded layer	SEONG HO-GYEONG	SUNGKYUNKWAN UNIVERSITY	KOR
P4-18	ABST-000096	Analysis of Bending Deformation of Cu Interconnects Based on Adhesive Methods in PI/PI Flexible Substrate	HAM JUBEEN	ANDONG NATIONAL UNIVERSITY	KOR
P4-19	ABST-000095	Time-domain thermoreflectance method for thermal property and reliability assessment	LEE DONG WOOK	KOREA ADVANCED INSTITUTE OF SCIENCE AND TECHNOLOGY (KAIST)	KOR
P4-20	ABST-000078	Microstructure and Mechanical property of Hybrid solder joints with different surface finished PCB	SUNG MINJAE	SUNGKYUNKWAN UNIVERSITY	KOR
P4-21	ABST-000068	Evaluation of Microstructural and Electrical Properties of Al doped Ni-Mn-Co based NTC temperature sensor	LEE EUNSEO	KYONGGI UNIVERSITY	KOR
P4-22	ABST-000033	Generative Models for Data Augmentation in Semiconductor Defect Inspection	LEE TAEWON	HOSEO UNIVERSITY	KOR
P4-23	ABST-000026	A study on improving the etch factor using Plasma Pretreatment in Semiconductor Burn-in test Board	PARK NAM-SON	THE TECH UNIVERSITY OF KOREA	KOR
P4-24	ABST-000025	Operando Measurements and Analyses of Temperature-distribution Evolution in High-Performance Semiconductors	CHEON MIN-JUN	HABAT NATIONAL UNIVERSITY	KOR
P4-25	ABST-000023	A Study on the SiC semiconductor package using virtual qualification technology for Automotive PTC system	YEON KYUBONG	KOREA AUTOMOTIVE TECHNOLOGY INSTITUTE (KATECH)	KOR
P4-26	ABST-000013	Measurement of adhesion energy by double cantilever beam (DCB) test taking into account machine compliance	KIM DONG-HYEON	UNIST	KOR
P4-27	ABST-000012	Optimization of the evaluation according to pre-stretching at evaluating the stretchability of stretchable devices	KIM DONG-HYEON	UNIST	KOR
P4-28	ABST-000011	Reliability Analysis of Polymer-based Copper Redistribution Layers (RDL) in Advanced Packaging Technologies	KWAK JI-YOUN	UNIST	KOR
P4-29	ABST-000195	Density effect on Mechanical properties and Reliability of Sintered Joints and Fabrication of Ag film by the Laser Bonding Method	KIM YUN-CHAN	KOREA INSTITUTE OF INDUSTRIAL TECHNOLOGY (KITECH)	KOR
P4-30	ABST-000105	Observation of TGV surface roughness according to heat treatment conditions	LEE JAEBEOM	KOREA INSTITUTE OF INDUSTRIAL TECHNOLOGY (KITECH)	KOR